ABSTRACT

Provided is a bonding composition which has a bleed-out suppression effect, and with which it is possible to obtain a bonded structure that has a bonded site having a high shear strength. This bonding composition contains a copper powder and a solvent. The solvent includes a first solvent that has a boiling point of 150°C or more and 300°C or less and a surface tension of 30 mN/m or more, and a second solvent that has a surface tension of less than 30 mN/m. The content of the first solvent is 0.1 mass% or more and 20 mass% or less with respect to the copper powder, and the content of the second solvent is 1.5 mass% or more and 20 mass% or less with respect to the copper powder.

[Figure 1]